(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
5 April 2012 (05.04.2012)

PCT

(10) International Publication Number
WO 2012/044683 A2

(51) International Patent Classification:
B24B 37/24 (2012.01) *B24B 49/10* (2006.01)
B24B 49/04 (2006.01)

(21) International Application Number:
PCT/US2011/053678

(22) International Filing Date:
28 September 2011 (28.09.2011)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
12/895,465 30 September 2010 (30.09.2010) US
12/895,479 30 September 2010 (30.09.2010) US
12/895,529 30 September 2010 (30.09.2010) US

(71) Applicant *(for all designated States except US)*: **NEXPLANAR CORPORATION** [US/US]; 7425 Nw Evergreen Parkway, Suite 150, Hillsboro, OR 97124 (US).

(72) Inventors; and
(75) Inventors/Applicants *(for US only)*: **WILLIAM, Allison, C.** [US/US]; 4243 NW Chaparral Terrace, Beaverton, OR 97006 (US). **SCOTT, Diane** [US/US]; 3140 NE Bryce Street, Portland, OR 97212 (US). **HUANG, Ping** [CN/US]; 7365 Howard Lane, Apt. 204, Eden Prairie, MN 55346 (US). **FRENTZEL, Richard** [US/US]; 31900 Serrento Drive, Murrieta, CA 92563 (US). **SIMPSON, Alexander, William** [GB/US]; 2515 Nw Overlook Drive, Apt.323, Hillsboro, OR 97124 (US).

(74) Agents: **VINCENT, Lester, J.** et al.; BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP, 1279 Oakmead Parkway, Sunnyvale, CA 94085-4040 (US).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *without international search report and to be republished upon receipt of that report (Rule 48.2(g))*

(54) Title: POLISHING PAD FOR EDDY CURRENT END-POINT DETECTION

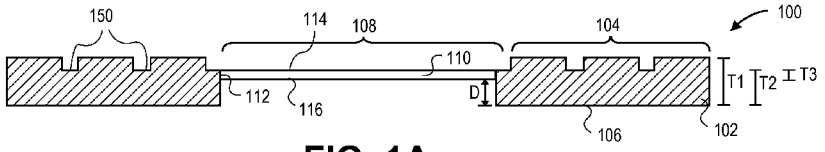


FIG. 1A

(57) Abstract: Polishing pads for polishing semiconductor substrates using eddy current end- point detection are described. Methods of fabricating polishing pads for polishing semiconductor substrates using eddy current end-point detection are also described.

WO 2012/044683 A2